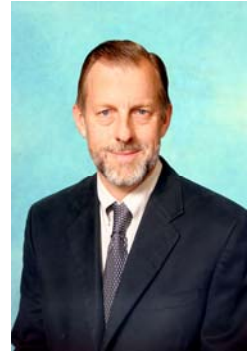


RapidIO Connections Q1 2007



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The RapidIO Trade Association: Delivering the Information Designers Need to Make Informed Choices

By Tom Cox, Executive Director

RapidIO Trade Association

Design-level interest RapidIO technology continues to gain attention among a wide range of engineers and managers developing diverse applications in the embedded computing and communications industry. Demand for RapidIO educational courses, seminars and white papers grows in sync with the speed of development and with the growth of the vast and continually expanding RapidIO eco-system of components and services.

This thirst for knowledge has progressed from “tell me how RapidIO technology compares to XXX switch fabric technology” to detailed discussions on advanced features offered by the RapidIO standard and application-specific questions like, “I incorporated RapidIO solutions in my test bed system. Do type 9 packets....?”

In response, the RapidIO Trade Association has long maintained www.RapidIO.org as a central information bank for this hot technology. To complement this wealth of information Embedded Planet, in partnership with the RapidIO Trade Association, now offers multi-day, in-depth RapidIO technical training programs. In addition, the RapidIO Trade Association expanded its sought-after Global Design Summits to drive information to designers in all four corners of the world. This Fall the RapidIO Trade Association will host a unique multi-country program, which provides an exceptional opportunity to interact with experts from all aspects of RapidIO embedded design.

The desire to understand the application of RapidIO technology in systems stems primarily from the features and capabilities defined in the RapidIO Specification 1.3. It is extremely clear that the RapidIO standard includes all the features that are in demand for high performance embedded systems. Combined with its extensive ecosystem of suppliers and components, designing with RapidIO technology has become synonymous to quick success. Extending the return on investment for designers working with this definitive standard, the recently completed RapidIO Specification 2.0 paves the way for the next generation of designs. Among other features, RapidIO Specification 2.0 adds advanced flow control for dataplane applications and an additional Physical layer which support 5 and 6.25 Gbps.

With the end of the so-called "Bus Wars," designers, system architects and their managers now look at the opportunity, market forecasts, and trends for RapidIO technology and the overall switch fabric market. Forecasting the growth and trends for the embedded market traditionally has been challenging, primarily because forecasters, trade journalists and 'Wall Streeters' (as Rick Merritt calls them in his contribution to this issue of *RapidIO Connections*) emphasized and focused on the high volume PC and consumer industries. When merged into these categories, the embedded sector gets lost. The high volume trends of these markets are assumed to be equal to and translate directly to the embedded space. While sometime true, more often this is not the case. A newly created market report, *Switch Fabrics 2007: RapidIO® Technology Takes the High Road To Embedded Systems* by Crystal Cube Consulting, for the first time examines the architectural standards that have made it to where the "rubber meets the road" with embedded switch fabric architectures and how those architectures are performing in the market.

Ernie Bergstrom, vice president of research and chief analyst of Crystal Cube Consulting says, "On the embedded computing board front Serial RapidIO is being used for embedded backplane systems in high-end applications. This puts RapidIO technology in a very strong position in the market place."

The white paper provides a five-year forecast on worldwide Serial RapidIO shipment and revenues, as well as DSP worldwide revenues including year-end 2006, as well as DSP worldwide revenue showing year-end 2006 along with projections into 2007 through 2011, and includes graphical illustrations of the forecast projections. Separate sections are devoted to an executive summary; a technology overview on each switch fabric examined including RapidIO, Ethernet 1GigE and 10GigE, PCI Express, Advanced Switching, and InfiniBand; the Serial RapidIO switch fabric five-year forecast, and guidance for telecom equipment manufacturers. A free download of this paper is now available on the RapidIO website.

The RapidIO Trade Association's mission is to develop and promote RapidIO technology; we continue to develop this leading edge technology and are committed to supporting every designer, manager, and system architect in their effort to learn and apply this technology. The RapidIO Trade Association continues to offer an expanding, diverse realm of information, which I encourage everyone to take advantage of in their

quest to satisfy their thirst for knowledge. In doing so, I ask you to take us to task in supporting your use of the RapidIO interconnect and to tell us what more you need to leverage this important technology in next generation applications.

European, North American, and Asian Global RapidIO Design Summits Scheduled for Fall 2007

The RapidIO® Trade Association announced its Fall 2007 Global RapidIO Design Summit schedule, with events slated for Europe, North America and Asia. These highly anticipated events provide engineering managers, system architects, and embedded product developers with practical information on RapidIO technology and products they can utilize now in their production products.

"These summits, developed specifically to illustrate how the embedded design community can achieve improved system performance and reliability with the high-speed, flexible RapidIO interconnect and fabric, are among the most highly attended RapidIO design events held each year," said Keith Woodard, chairman of the RapidIO Trade Association Customer Programs sub-committee. "The member companies of the Trade Association are dramatically expanding the presentations and hardware demonstrations this year, with a focus on practical designs and implementations using RapidIO interconnect technology."

The free, full-day events include two tracks of technical sessions highlighting RapidIO technology, applications examples, software considerations, practical design recommendations, and RapidIO products. In addition, a technology lab will feature multi-vendor RapidIO interoperability demonstrations using state-of-the-art RapidIO products from multiple vendors. Technical personnel from Trade Association member companies will provide a unique opportunity for attendees to interact directly with RapidIO technology experts and get their specific questions answered. A complimentary light breakfast, lunch and snacks will be provided.

- Munich, Germany Monday, 17 September 2007
- Paris, France Thursday, 20 September 2007
- Boston, Massachusetts, United States Thursday, 04 October 2007
- Seoul, Korea Monday, 05 November 2007
- Shanghai, People's Republic of China Wednesday, 07 November 2007
- Shenzhen, People's Republic of China Friday, 09 November 2007
- Hyderabad or Chennai, India Tuesday, 13 November 2007
- Bangalore, India Thursday, 15 November 2007

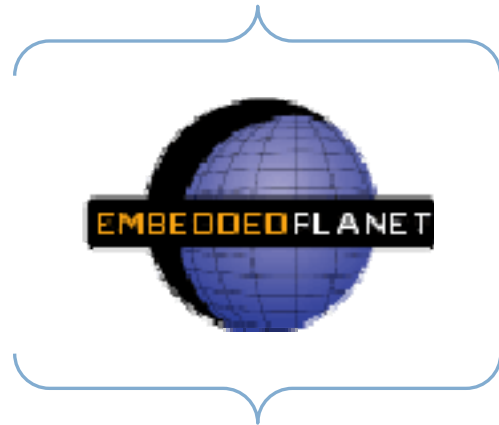
Additional details can be found on www.RapidIO.org. Dates of these events are subject to change, and interested attendees are asked to check the web site often for location and agenda information.

Hosted by the RapidIO Trade Association, the 2007 Global Design Summit presentations and demonstrations are supplied by the Trade Association member companies.

RapidIO Trade Association Teams with Embedded Planet to Deliver World Class RapidIO Design Training

Embedded Planet is working exclusively with the RapidIO Trade Association to design and deliver hardware and software curriculum for embedded engineers and designers.

The RapidIO® Trade Association and Embedded Planet announced they have partnered to create a RapidIO technology training curriculum that will provide hands-on training for designers employing RapidIO technology in high performance, innovative systems. Embedded Planet will leverage its years of professional training experience, first-hand knowledge of RapidIO design processes, and input from the RapidIO Trade Association members to develop and deliver a set of high quality training courses.



"The RapidIO eco-system continues to grow as OEMs and ODMs discover the powerful benefits of designing with RapidIO technology," said Tom Cox, executive director of the RapidIO Trade Association. "With this new training curriculum from Embedded Planet, independent testing through RIOLAB, more than a hundred products, and a growing Trade Association community, designers have everything they need to create high-performance systems."

The training program is designed for engineers designing with Serial RapidIO for the first time as well as for experienced designers seeking to hone their knowledge and keep abreast of RapidIO technology developments. The courses, RapidIO Hardware Design and RapidIO Software Design, are comprehensive two-day sessions which focus on both the RapidIO 1.3 and the imminent RapidIO 2.0 specifications. The curriculum provides an overview of Serial RapidIO, packet switching, as well as design tips for the logical, transport and physical layers. The program can be combined into an in-depth four-day course. For information visit www.EmbeddedPlanet.com/training/rapidio_training.asp.

"Embedded Planet is pleased to be working with the RapidIO Trade Association to deliver training on a technology that is becoming increasingly important in the creation of next generation embedded systems," said Mike McCullough, director of professional services for Embedded Planet. "Quality training is a vital component of enabling engineers to reach high levels of productivity quickly and meet today's demanding product schedules. Our experience in training, software, and hardware development allows us to deliver a unique training course that covers the breadth of issues facing engineers designing with RapidIO technology."

Embedded Planet's trainers have been developing and providing leading-edge training programs for more than a decade, helping embedded systems developers as they produce world-class software and systems on schedule and within tight budget constraints. The company's training is recognized as a key element in reducing time-to-productivity and developing more agile design teams.

Embedded Planet, founded in 1997, is a leading full service single board computer and embedded systems solution provider. The company's unique set of capabilities enables it to support organizations through the entire lifecycle of product development with customized training at project launch through high quality volume production services during product deployment. Embedded Planet's integrated hardware and software systems and training capabilities accelerate time to market for OEMs in the networking, military, industrial, and medical markets. The company's products support a broad range of processors, embedded operating systems, and form factors. For more information, please see www.embeddedplanet.com or email info@embeddedplanet.com.

Industry Insights

Under the Radar, RapidIO is Doing Fine

By Rick Merritt, Editor-at-Large, EE Times

Rick Merritt writes a blog on interconnects at <http://interconnects.blogspot.com/>

When graciously asked to write a short article for this month's newsletter, I had to admit I wasn't sure what to say about the RapidIO interconnect and had to do a little research. Truth be told, RapidIO technology and the whole embedded sector where it lives tends to fly under the radar for many trade journalists and Wall Streeters who cover technology—even supposedly expert *EE Times*

editors and bloggers like myself! We tend to give most of our attention to mainstream



computing with its big volumes and interesting Intel vs. AMD and Microsoft vs. Linux brawls.

Forgive us our myopia as we follow the big money. In-Stat said PCI Express shipped last year in a whopping 224 million systems, mainly PCs, compared to less than 500,000 systems that used RapidIO products. Similarly, numbers for the Ethernet juggernaut are off the top end of the scale. Nevertheless, if you scratch the surface, RapidIO technology has had a good year.

The same In-Stat report I wrote about back in March said the RapidIO standard has a strong base in several embedded sectors. The market watcher actually predicts it will dominate in areas such as wireless base stations and medical and defense systems. In a March report on the outlook for backplane-based systems, top engineers from Alcatel-Lucent told me there are high performance niches where they will use RapidIO technology because Express just doesn't fly. A February report from my colleague Loring Wirbel discussed the flow control and quality of service mechanisms coming in RapidIO Specification 2.0 which will support 6.125 Gbit/second data rates, surpassing Express 2.0 with its 5 Gbit/second ceiling. Altera gave a nod to the RapidIO standard as an established interface when they agreed to support it in their new line of Arria low-cost FPGAs in May.

Indeed, in the embedded space, RapidIO technology has become something of an incumbent, originally designed by embedded systems engineers primarily as a chip-to-chip interface for their PowerPC processors and DSPs. It didn't hurt that last year Advanced Switching, Intel's push to retool Express for embedded, went belly up. Of course, many engineers, including the crew at StarGen, are realizing Express has long legs in computing that will carry it into use in many embedded systems. But the RapidIO standard has clearly established its roots, set its road map and will grow for years to come.

RapidIO technology may fly under the radar sometimes, but insiders know it is also being used inside the radar, and the base station, and that high-end telco switch and...

Selected URLs for more information:

Article on InStat's interconnect report:

www.eetimes.com/showArticle.jhtml?articleID=197700188

EE Times report on RapidIO Specification 2.0:

www.eetimes.com/showArticle.jhtml?articleID=197006130

No winner yet in backplane brawl:

www.eetimes.com/showArticle.jhtml?articleID=198001315

Altera's Arria support RIO, Express and Ethernet:

www.eetimes.com/showArticle.jhtml?articleID=199203338

Advanced Switching goes belly up:

www.eetimes.com/showArticle.jhtml?articleID=190400383

Celebrating Success

RapidIO Interconnect Standard: Easy as Buying a Car

Bill Beane, Senior Product Manager, IDT

Any new interconnect standard has to go through a start-up process, building awareness, knowledge, and preference among suppliers and customers. In many ways, it's analogous to buying a car. First, you look through a bunch of brochures. Then you want to go see it in person – walk around it, sit in it, kick the tires. If that feels right, you take it for a test drive; put it through its paces. Finally, when you're satisfied it meets your needs and your budget; you drive it home from the lot.



In order for a new interconnect standard to be successful, it has to be able to support this full process – ultimately, “driving it home” translates to design wins, to systems being built using the new interconnect. This process applies to suppliers as well as to consumers. In our case, we at IDT studied the RapidIO technology thoroughly before deciding to become a vendor. As the developer of integrated mixed-signal solutions for wireless infrastructure and other embedded processing applications, we wanted to make sure that it was the right fit as a technology on which to build our enhanced switching and memory solutions.

We were satisfied that it provided the right balance of cost and performance, with the flexibility and scalability needed in the markets and applications we serve, and that it had the right ecosystem of key suppliers providing components, hardware, software, and diagnostic tools to give it the critical mass needed to sustain itself across multiple generations of platforms. This process done, our “test drive” complete, we made our own decision to “buy,” through incorporating Serial RapidIO in our pre-processing switch devices and serial buffer solutions, providing enhanced support for DSP and other end-point clusters in a variety of applications.

Having become one of many RapidIO vendors, we in IDT then turned our attention to supporting the evaluation and purchase process for our own customers. Our specifications, applications notes, and technical articles provide for “brochure study,” while our simulation tools, development platforms, and advanced software solutions provide ample ability to “kick the tires” and “test-drive” our components and the underlying RapidIO technology. We see this going on throughout the ecosystem – and the success of the standard is apparent in the rapidly increasing number of

customers and applications that we are supporting. Our customers have become savvy consumers – they know what they want in their systems, they know the capabilities of RapidIO technology as it applies to their applications, and they’ve checked out other options. They’re giving our products a thorough check-out, and they’re driving off our lot well-satisfied with the purchase they’ve made.

To make a standard work, there has to be a sustainable market and a strong ecosystem. RapidIO products are readily available through multiple suppliers, and deliver on the performance and cost requirements for embedded applications. From wireless and wireline communications to computing and storage and even into critical embedded applications such as military sensor platforms and medical imaging, the interconnect is providing system-level features and benefits that far outstrip the abilities of non-tailored standards. If you haven’t taken the chance to do so yet, you owe it to yourself to “test drive” some RapidIO solutions. We’re confident you’ll drive home happy, another satisfied customer. You can find IDT RapidIO-based products at www.idt.com, and the RapidIO Trade Association maintains a product showcase of member companies’ solutions at www.rapidio.org.

Technical Insights

LTE Test Bed – Excerpt

By Bernt Johansson and Tomas Sundin, Ericsson

The Third Generation Partnership Project (3GPP) is specifying the long-term evolution of third-generation cellular systems to meet demands for higher user bit rates. Ericsson has thus developed a test bed to evaluate new access technologies and to investigate the suitability of new implementation technologies for future radio-access products. The authors explain the access concept and anticipated requirements for LTE and describe the test-bed system, architecture, subsystems, and technology.

Background

In September 2006, 3GPP finalized a study item called *Evolved UTRA* and *UTRAN*. The purpose of the study was to define the long-term evolution (LTE) of 3GPP access technology in order to keep it competitive even in the distant future.¹⁻² A corresponding work item is scheduled for completion in the second half of 2007. The 3GPP also conducted a parallel study, called *System Architecture Evolution (SAE)*, to outline the evolution of the core network.



Introduction to LTE

The 3GPP study item began by setting requirements and defining the scope of LTE. Examples of these requirements are

- improved instantaneous peak data rates – 100Mbps in the downlink and 50Mbps in the uplink;
- reduced latency – less than 100ms transition from camped state to active state, less than 50ms transition from dormant state to active state, and less than 5ms IP packet latency in the user plane in an unloaded system;
- improved system performance – two- to four-fold increase in downlink bit rates compared with a basic release 6 system (HSDPA), and two- to three-fold increase in uplink bit rates compared with a basic release 6 system (E-DCH); and
- improved spectrum flexibility – ability to deploy the system in many different frequency bands, in paired and unpaired spectrum, and with different spectrum allocations (for example, 1.25, 2.5, 5.0, 10.0, 15.0 and 20MHz).

The requirements were also used as input for determining the choice of air interface. To fulfill the requirements put on spectrum flexibility and peak data rates, the study item concluded that the air interface in the downlink should be based on orthogonal frequency-division multiplexing (OFDM). This approach yields a frequency structure that splits data over a large number of individual subcarriers with a spacing of 15kHz. The smallest addressable unit, called a resource block, is defined as 12 consecutive subcarriers in frequency and 14 consecutive symbols in time. The resource block is thus 180kHz in the frequency domain and equal to 1ms (or one sub-frame) in the time domain. A sub-frame is also the minimum transmission time interval (TTI). Short TTIs favor the requirements put on latency in the user plane. The main method of fulfilling the requirements for peak data rates calls for the transmission of parallel streams of data to a single terminal using multiple-input multiple-output (MIMO) techniques.

For the uplink, the study item recommended a single-carrier-based frequency division multiple access (FDMA) solution with dynamic bandwidth. This approach allows for a power-efficient implementation of the user terminal. The basic parameters, such as sub-frame and TTI, match those of the downlink.

Ericsson's LTE test bed thus uses cyclic-prefix OFDM (CP-OFDM) technology in the downlink and localized or interleaved FDMA technology in the uplink. At present, in a single-stream configuration from a single mobile user to the radio base station (RBS), it supports transmission rates of up to nearly 80Mbps in the downlink and 25Mbps in the uplink. The addition of three more streams in the downlink will give the test bed a peak data rate of nearly 300Mbps.

The LTE test bed is currently limited to a single cell configuration without support for radio resource management, admission control, or handover between cells or sectors. Apart from basic radio and baseband (BB) capabilities, it implements

medium access control (MAC), radio link control (RLC), and a simple interface to applications and services. It has also been prepared to work with advanced antenna solutions. Therefore, the LTE access network can optimize transmission according to a user's location and needs – that is, it can combine several streams, form beams (beam forming) for longer range, or employ other combinations of transmission. For the complete paper visit, <http://www.rapidio.org/news/mc/> or http://www.ericsson.com/ericsson/corpinfo/publications/review/2007_01/files/2_lte_web.pdf.

In the News

The RapidIO Trade Association, its members and their products continue to be sought after news in the industry.

- **Altera Corporation** launched low-cost Arria GX family Transceiver-Based FPGAs. Arria GX FPGAs are optimized to support PCI Express (PCIe), Gigabit Ethernet (GbE) and Serial RapidIO (SRIO) standards up to 2.5 Gbps. It features the proven Stratix II GX transceiver technology; flip-chip packages for superior signal integrity, software tools and verified intellectual property (IP) cores. www.rapidio.org/news/pr/view?item_key=a02079abd6de741737d119e8e1946a0f850b0dda
- **BittWare Inc.**, announced their partnership with CorEdge Networks and the release of their RapidTCA Development System, a unique development environment for Advanced Mezzanine Card (AdvancedMC™) and MicroTCA designs. BittWare's RapidTCA Development System combines the PicoTCA 1U stand-alone test and development system from CorEdge Networks, with the hybrid signal processing capabilities of BittWare's AdvancedMC products. The flexible and portable design of BittWare's RapidTCA Development System coupled with its low cost enables customers to quickly and cost-effectively bring their AdvancedMC and MicroTCA designs to life. www.rapidio.org/news/pr/view?item_key=15b39479a0ba6845e8c94c1ba8f81a5430ef366e
- **FuturePlus Systems** introduced the FS4405, FS4415, and FS4416, low-cost PCI Express (PCIe®) and Serial RapidIO® protocol analysis tools for use with Tektronix TLA 7000 logic analyzers. They will be used by embedded systems designers involved in the development of computers and peripherals incorporating the PCIe and Serial RapidIO architectures. www.rapidio.org/news/pr/view?item_key=2fe63c1bf3ce0ee0a8c46c369ad2509637bb4b72
- **Mercury Computer Systems, Inc.** announced that it has provided silicon intellectual property (SIP) to Raytheon Space and Airborne Systems for the development of the MONARCH (Morphable Networked Micro-Architecture) fully programmable, system-on-a-chip-processor. www.rapidio.org/news/pr/view?item_key=c309aa12f363d15889f6583a9066161754ae49e1

- **RIOLAB**, a division of Fabric Embedded Tools Corporation and the world's only independent RapidIO® interoperability testing facility, announced that the Tundra Semiconductor Tsi578, (10GCLYZ2), Serial RapidIO switch is a Device Interoperability Level 3 (DIL-3) Qualified Device, having successfully passed DIL-3, DIL-2 and DIL-1 testing against all other vendor devices in the RIOLAB hardware library.
www.rapidio.org/news/pr/view?item_key=e7524a05fff2485385b1c644af1f0dfdec04abce
- **Texas Instruments Incorporated** (TI) announced the immediate availability of a TMS320C6455 digital signal processor (DSP) evaluation module (EVM) and a TMS320C6455 DSP starter kit (DSK), both with a Serial RapidIO bus interface. The C6455 DSP, based on the TMS320C64x+™ DSP core and at the heart of the EVM and DSK, is now sampling, bringing together TI's highest performing DSP architecture with Serial RapidIO support to boost performance and I/O bandwidth in high-end and multichannel applications such as video and voice transcoding, videoconferencing servers, high-definition (HD) video encoding and mixer systems, wireless base station transceivers, HD radio, medical imaging, and photo labs and printing. www.ti.com/c6455pr
- **Texas Instruments Incorporated** (TI) announced its high-performance TMS320C6455 digital signal processors (DSPs) have been selected by Raytheon for use in the U.S. Navy's DDG 1000 Zumwalt Class Destroyer program. Raytheon serves as the main mission systems equipment integrator for all electronic and combat systems for the Navy. Tuned for a myriad of infrastructure equipments including high-end telecom, wireless infrastructure, and video and imaging applications, TI's 1-GHz C6455 DSP is the processing workhorse for ATRIM(TM) (Acoustic Transmit Receive Integration Module) Sonar, a sonar signal sub-system that incorporates multiple boards, each processing four channels of sonar. Peak performance, small code size, large on-chip memory and integrated peripherals, including the Ethernet MAC and Serial RapidIO(R) bus for inter-processor communications, and optical Ethernet interface, all elevated the selection of the C6455 DSP to support the design and development of this revolutionary surface combatant. www.rapidio.org/news/pr/view?item_key=9091cfef453019cdc351d5f61d9be579905138b1
- **Tundra Semiconductor Corporation** announced a collaboration with Ericsson (NASDAQ:ERIC), the leading wireless infrastructure provider, to license the Switching Module of a MicroTCA Carrier Hub (MCH) card, designed by Ericsson with Tundra's Tsi578 Serial RapidIO® Switch. The license granted to Tundra includes sub-licensing rights and Tundra will be sub-licensing the design as the Tsi578 MicroTCA Switching Module (MSM), thereby broadening the availability of Serial RapidIO-based MicroTCA Systems.
www.rapidio.org/news/pr/view?item_key=332a3f7d01081b5d8e488667c1144b8cc8d1d2a3

In the Spotlight

An abundance of articles focusing on designing with RapidIO technology have appeared in the past weeks. Below, we've included links to some of the best.

Test and Measurement.com

Tundra Semiconductor RapidIO Switch Passes Level 3 Device Interoperability Test

<http://www.testandmeasurement.com/content/news/article.asp?DocID=%7B111D3AB9-C0C5-464A-9C21-B632BB4B2969%7D&Bucket=Current+Headlines&VNETCOOKIE=NO>

Electronic Design

When It Comes To Backplanes, Give RapidIO A Try

<http://www.elecdesign.com/Articles/Index.cfm?AD=1&ArticleID=15268#>

Electronic Design

High-Speed Serial Technology Drives Board Interconnects

<http://www.elecdesign.com/Articles/Index.cfm?ArticleID=15348&pg=1>

Sys-con Media

PCIe, RapidIO, and Ethernet for High-Speed Interconnects to Be Focus of Linley Tech Seminar

<http://www.sys-con.com/read/367490.htm>

Electronicstalk

Training course on RapidIO technology

<http://www.electronicstalk.com/news/rai/rai121.html>

Network Systems DesignLine

Tip of the Week: Achieve system scalability with switch fabrics in CompactPCI

<http://networksystemsdesignline.com/howto/showArticle.jhtml;jsessionid=UJ4WTX54QZ1XCQSNLSCCKHA?articleID=199001121>

Embedded Computing Design

Perspectives on market prospects

<http://www.embedded-computing.com/departments/foreword/2007/04/>




Electronic Design

RapidIO Versus Ethernet: What You Really Need To Know

<http://www.elecdesign.com/Articles/ArticleID/15202/15202.html>

Events

Meet up with RapidIO Trade Association members and see their products first hand at a range of industry events. Dates subject to change, check <http://www.rapidio.org/events/list/> for current details and information.

Event	Description	Date and Location
Freescale Technology Forum	http://www.freescale.com/FTF	June 25-28, 2007 Orlando, FL
RapidIO Radio 	Featuring experts from Texas Instruments.	Download available July, 2007
RapidIO Radio 	Featuring experts from IDT.	Download available September, 2007
RapidIO Radio 	Featuring experts from Silicon Turnkey Express.	Download available November, 2007
Global RapidIO Design Summits	The Global RapidIO Design Summit provides engineering managers, system architects, and embedded product developers with practical information on RapidIO technology and products they can utilize immediately in their production products. The free, full-day events include two tracks of technical sessions highlighting RapidIO technology, applications examples, software considerations, practical design recommendations, and RapidIO products.	Munich, Germany – September 17, 2007 Paris, France –September 20, 2007
Global RapidIO Design Summits	The Global RapidIO Design Summit provides engineering managers, system architects, and embedded product developers with practical information on RapidIO technology and products they can utilize immediately in their production products.	Boston, Massachusetts – October 4, 2007
Global RapidIO Design Summits	The Global RapidIO Design Summit provides engineering managers, system architects, and embedded product developers with practical information on RapidIO technology and products they can utilize immediately in their production products.	Seoul, Korea – November 5, 2007 Shanghai, PRC – November 7, 2007 Shenzhen, PRC – November 9, 2007 Hyderabad or Chennai, India – November 13, 2007 Bangalore, India – November 15, 2007

Connect and Contribute

RapidIO Connections welcomes your comments, ideas, questions and contributions.

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